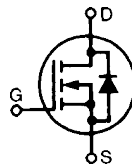


TrenchT2™ Power MOSFET

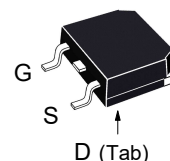
IXTH360N055T2 IXTT360N055T2

$V_{DSS} = 55V$
 $I_{D25} = 360A$
 $R_{DS(on)} \leq 2.4m\Omega$

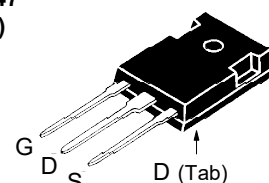
N-Channel Enhancement Mode
 Avalanche Rated
 Fast Intrinsic Diode



TO-268
(IXTT)



TO-247
(IXTH)



G = Gate D = Drain
 S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ C$ to $175^\circ C$	55	V
V_{DGR}	$T_J = 25^\circ C$ to $175^\circ C$, $R_{GS} = 1M\Omega$	55	V
V_{GSM}	Transient	± 20	V
I_{D25}	$T_C = 25^\circ C$ (Chip Capability)	360	A
I_{LRMS}	Lead Current Limit, RMS	160	A
I_{DM}	$T_C = 25^\circ C$, Pulse Width Limited by T_{JM}	900	A
I_A	$T_C = 25^\circ C$	180	A
E_{AS}	$T_C = 25^\circ C$	960	mJ
P_D	$T_C = 25^\circ C$	935	W
T_J		-55 ... +175	$^\circ C$
T_{JM}		175	$^\circ C$
T_{stg}		-55 ... +175	$^\circ C$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ C$
T_{SOLD}	Plastic Body for 10s	260	$^\circ C$
M_d	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

Symbol	Test Conditions ($T_J = 25^\circ C$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V$, $I_D = 250\mu A$	55		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.0		4.0 V
I_{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			± 200 nA
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_J = 150^\circ C$			10 μA
				300 μA
$R_{DS(on)}$	$V_{GS} = 10V$, $I_D = 100A$, Note 1			2.4 m Ω

Features

- International Standard Package
- $175^\circ C$ Operating Temperature
- High Current Handling Capability
- Avalanche Rated
- Fast Intrinsic Diode
- Low $R_{DS(on)}$

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- DC/DC Converters and Off-line UPS
- Primary- Side Switch
- High Current Switching Applications

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 60\text{A}$, Note 1	65	110	S
C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$		20	nF
C_{oss}			2650	pF
C_{rss}			480	pF
R_{Gi}	Gate Input Resistance		1.6	Ω
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 100\text{A}$ $R_G = 2\Omega$ (External)		30	ns
t_r			23	ns
$t_{d(off)}$			62	ns
t_f			56	ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$		330	nC
Q_{gs}			76	nC
Q_{gd}			87	nC
R_{thJC}	TO-247			0.16 $^\circ\text{C/W}$
R_{thCH}			0.21	$^\circ\text{C/W}$

Source-Drain Diode

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_S	$V_{GS} = 0\text{V}$			360 A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			1440 A
V_{SD}	$I_F = 100\text{A}$, $V_{GS} = 0\text{V}$, Note 1			1.3 V
t_{rr}	$I_F = 150\text{A}$, $V_{GS} = 0\text{V}$ $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 27\text{V}$		78	ns
I_{RM}			4.2	A
Q_{RM}			164	nC

Note 1. Pulse test, $t \leq 300\mu\text{s}$; duty cycle, $d \leq 2\%$.

Littelfuse reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065B1	6,683,344	6,727,585	7,005,734B2	7,157,338B2
by one or more of the following U.S. patents:	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123B1	6,534,343	6,710,405B2	6,759,692	7,063,975B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

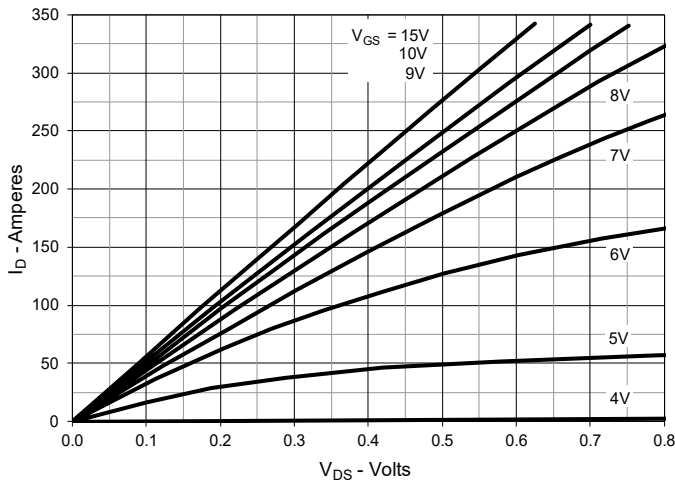


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

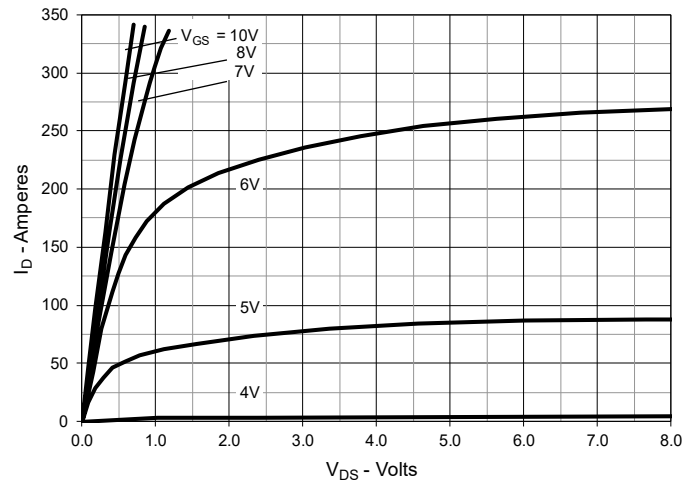


Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

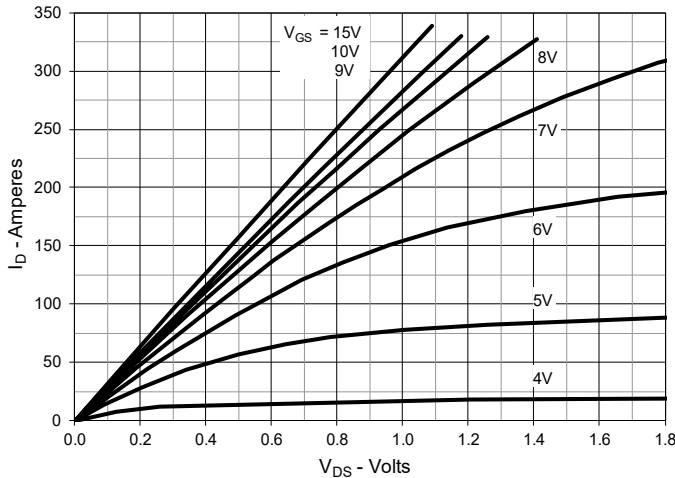


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 180\text{A}$ Value vs. Junction Temperature

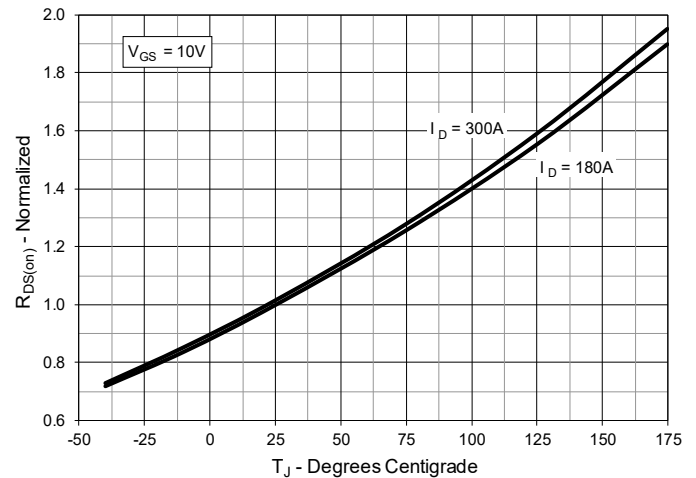


Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 180\text{A}$ Value vs. Drain Current

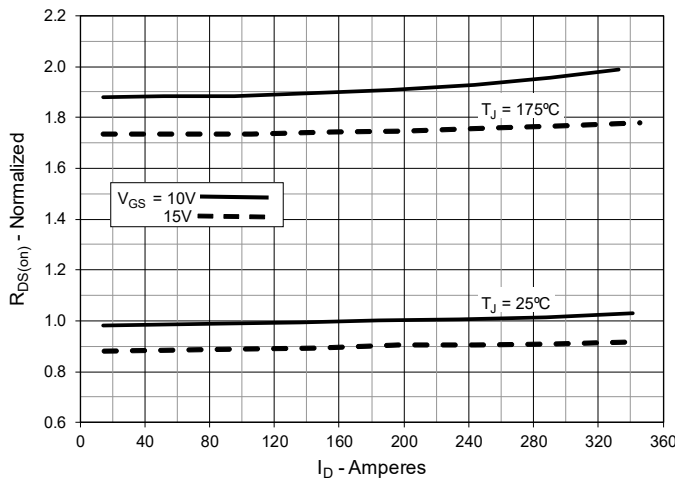


Fig. 6. Drain Current vs. Case Temperature

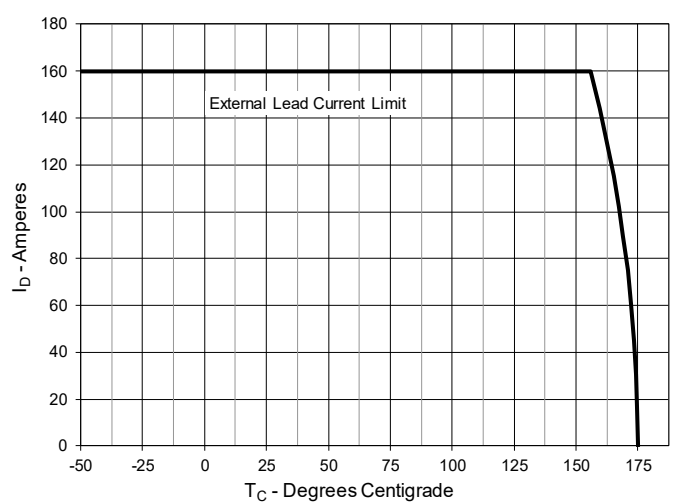


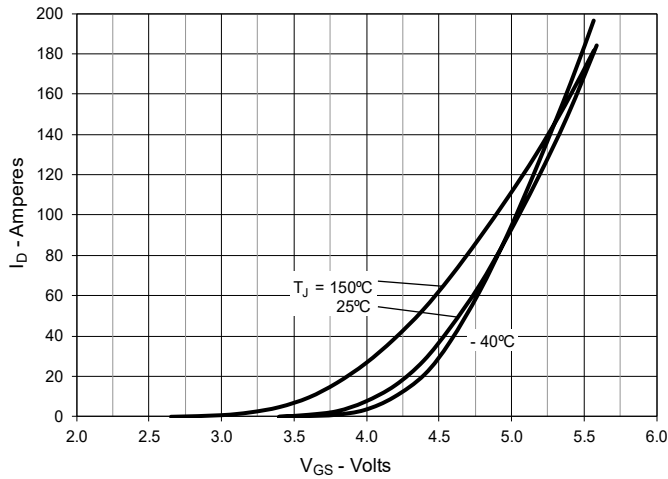
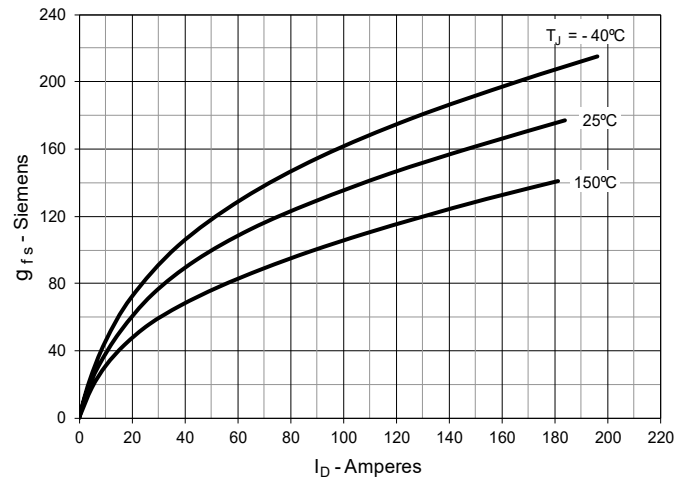
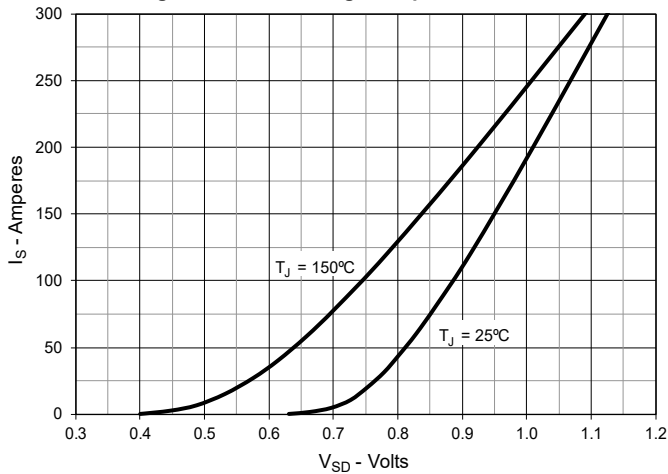
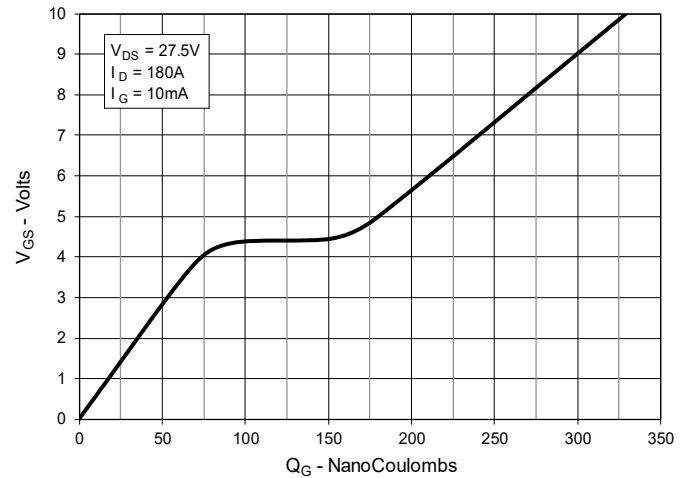
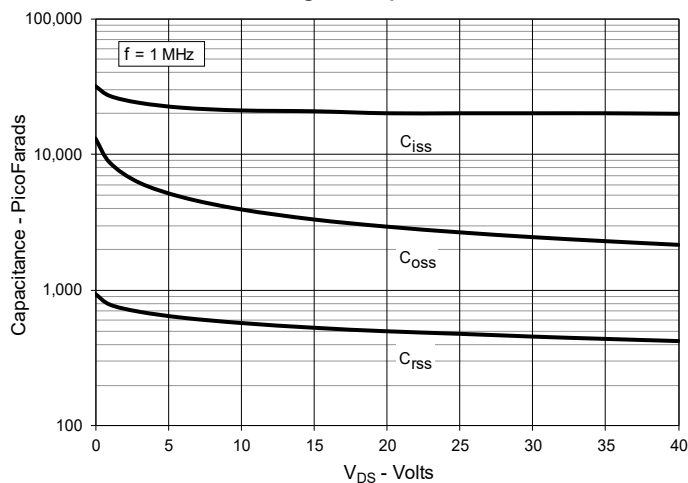
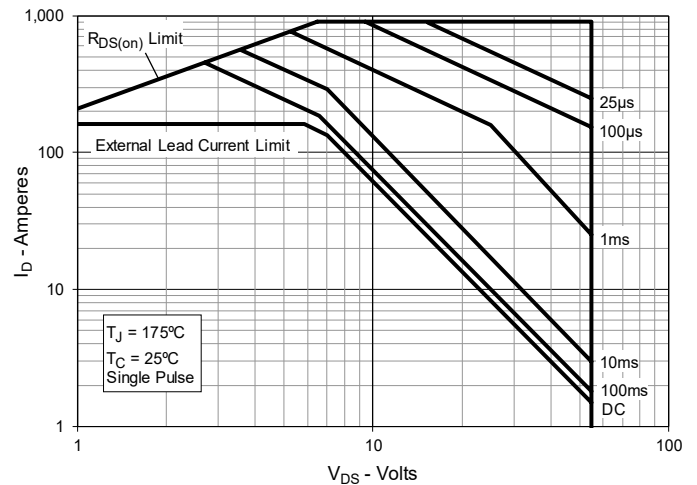
Fig. 7. Input Admittance

Fig. 8. Transconductance

Fig. 9. Forward Voltage Drop of Intrinsic Diode

Fig. 10. Gate Charge

Fig. 11. Capacitance

Fig. 12. Forward-Bias Safe Operating Area


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

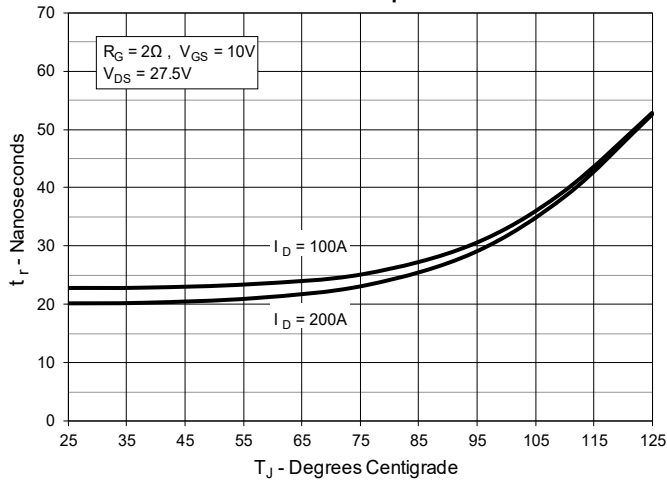


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

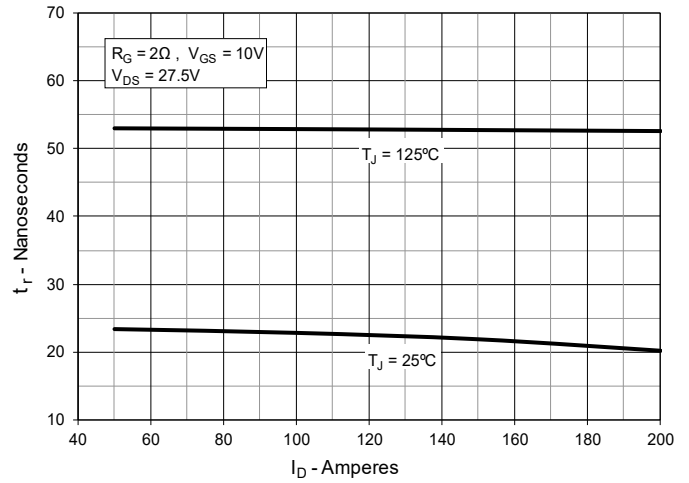


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

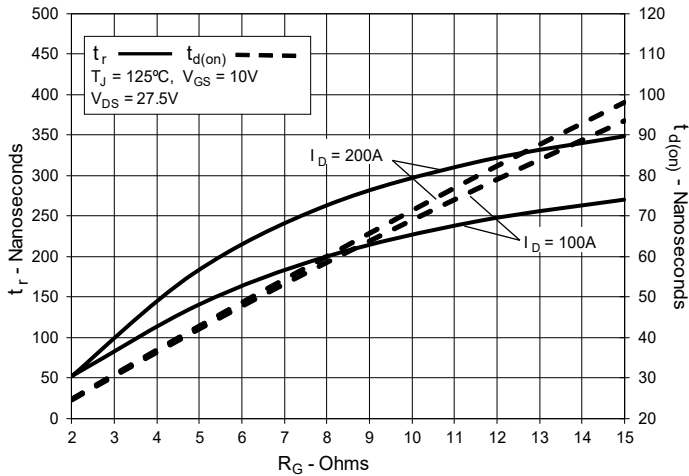


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

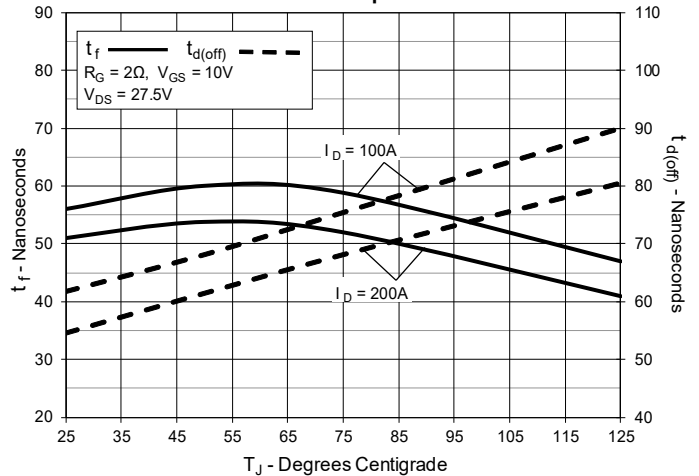


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

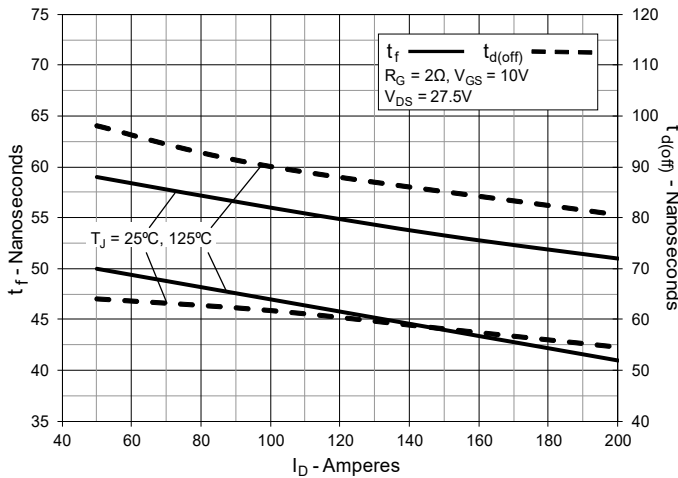


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

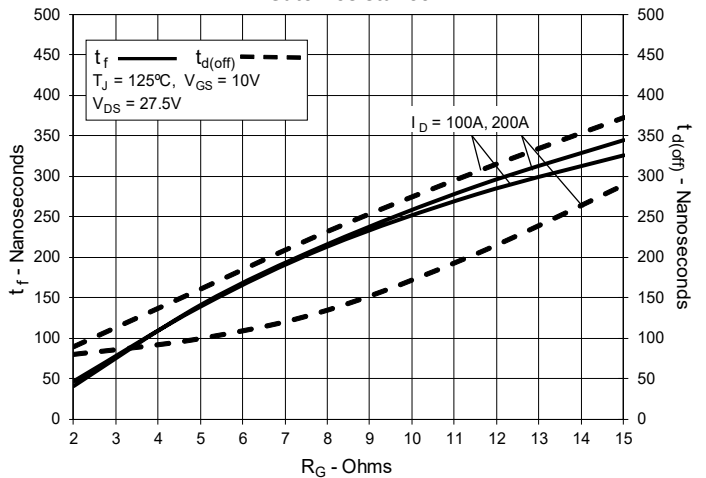
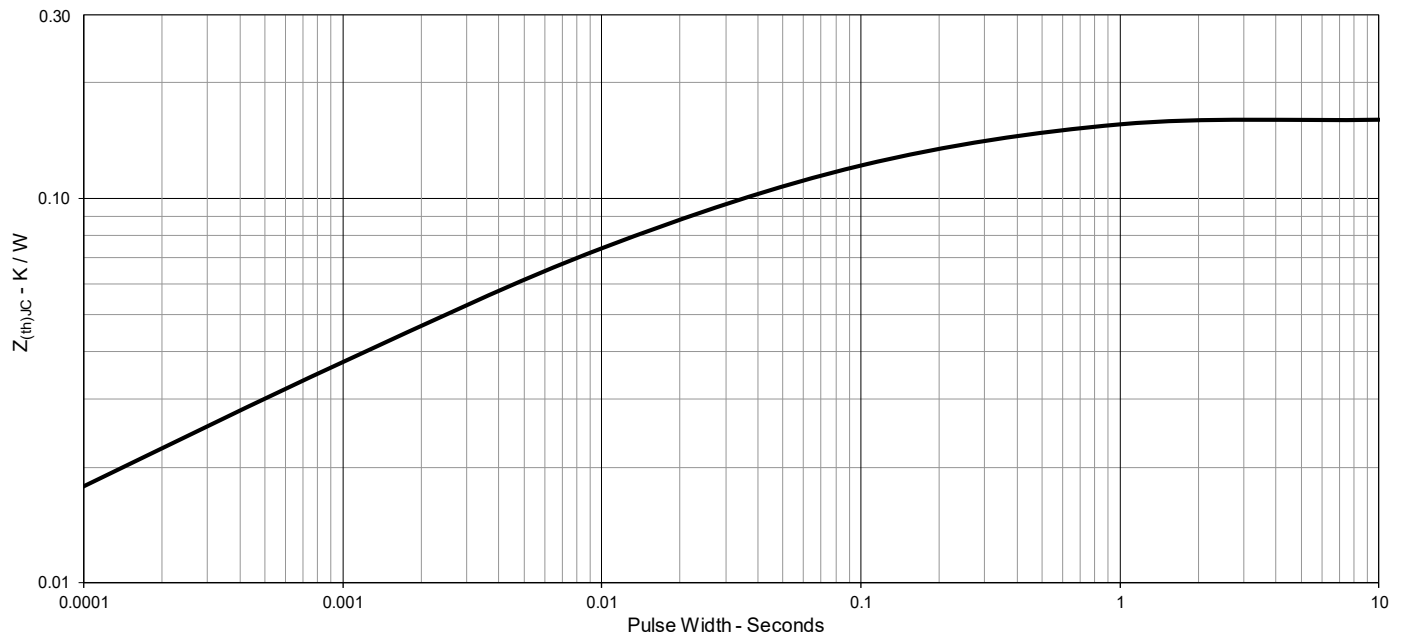
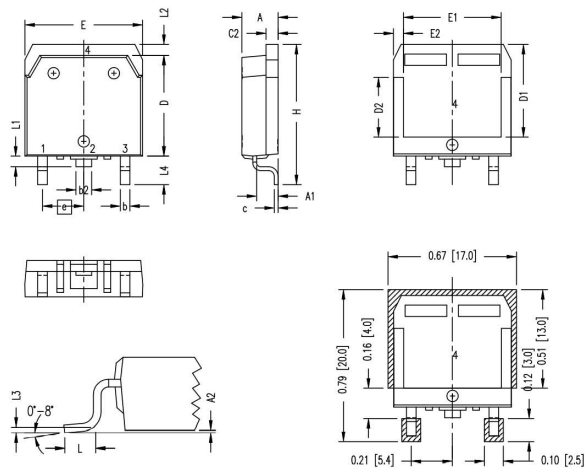


Fig. 19. Maximum Transient Thermal Impedance



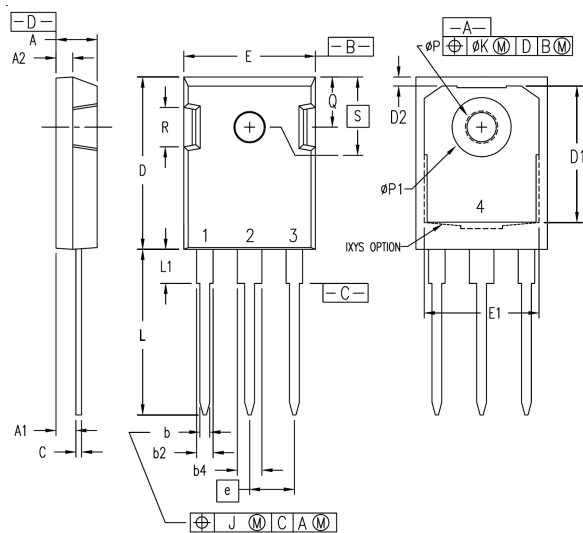
TO-268 Outline



1 - Gate
 2,4 - Drain
 3 - Source

SYM	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.193	0.201	4.90	5.10
A1	0.106	0.114	2.70	2.90
A2	0.001	0.010	0.02	0.25
b	0.045	0.057	1.15	1.45
b2	0.075	0.083	1.90	2.10
c	0.016	0.026	0.40	0.65
C2	0.057	0.063	1.45	1.60
D	0.543	0.551	13.80	14.00
D1	0.488	0.500	12.40	12.70
D2	0.320	0.335	8.13	8.50
E	0.624	0.632	15.85	16.05
E1	0.524	0.535	13.30	13.60
E2	0.045	0.055	1.14	1.39
e	0.215	BSC	5.45	BSC
H	0.736	0.752	18.70	19.10
L	0.094	0.106	2.40	2.70
L1	0.047	0.055	1.20	1.40
L2	0.039	0.045	1.000	1.15
L3	0.010	BSC	0.25	BSC
L4	0.150	0.161	3.80	4.10

TO-247 Outline



1 - Gate
 2,4 - Drain
 3 - Source

SYM	INCHES		INCHES	
	MIN	MAX	MIN	MAX
A	0.190	0.205	4.83	5.21
A1	0.090	0.100	2.29	2.54
A2	0.075	0.085	1.91	2.16
b	0.045	0.055	1.14	1.40
b2	0.075	0.087	1.91	2.20
b4	0.115	0.126	2.92	3.20
C	0.024	0.031	0.61	0.80
D	0.819	0.840	20.80	21.34
D1	0.650	0.690	16.51	17.53
D2	0.035	0.050	0.89	1.27
E	0.620	0.635	15.57	16.13
E1	0.545	0.565	13.84	14.35
e	0.215 BSC		5.45 BSC	
J	--	0.010	--	0.250
K	--	0.025	--	0.640
L	0.780	0.810	19.81	20.57
L1	0.150	0.170	3.81	4.32
ØP	0.140	0.144	3.55	3.65
ØP1	0.275	0.290	6.99	7.37
Q	0.220	0.244	5.59	6.20
R	0.170	0.190	4.32	4.83
S	0.242 BSC		6.15 BSC	

